

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended). A method for producing an electrical device comprising the steps of:
  - forming a flat lead frame including a plurality of leads extending radially from a central opening, the lead frame having opposing upper and lower surfaces;
  - mounting the lead frame and an integrated circuit die onto a strip of adhesive tape such that a lower surface of the die contacts the adhesive tape and the die is located in the central opening, and the lower surface of the lead frame also contacts the adhesive tape;
  - forming a plastic casing over an upper surface of the die and the upper surface of the lead frame; and
  - removing the adhesive tape to expose the lower surfaces of the die and the lead frame, whereby exposed portions of the lead frame form the only externally accessible I/O contacts for the package.
2. (Original) The method according to claim 1, wherein the die includes a plurality of die bond pads, and the method further comprises the step of electrically connecting each of the die bond pads to a selected one of the plurality of leads.
3. (Original) The method of claim 2, wherein the step of electrically connecting comprises wire bonding.
4. (Original) The method of claim 1, wherein the step of forming the lead frame comprises etching a metal sheet.
5. (Original) The method of claim 1, wherein the step of forming the lead frame comprises stamping a metal sheet.
6. (Original) The method of claim 1, wherein the step of forming the plastic casing comprises molding plastic onto the upper surfaces of the die and the lead frame.
7. (New) A method of packaging an integrated circuit comprising:
  - providing a lead frame including a plurality of leads and a central opening, the lead frame having opposing upper and lower surfaces;

mounting the lead frame and an integrated circuit die onto a strip of adhesive tape such that a lower surface of the die contacts the adhesive tape and the die is located in the central opening, and the lower surface of the lead frame also contacts the adhesive tape;

molding a plastic casing over an upper surface of the die and the upper surface of the lead frame; and

removing the adhesive tape to expose the lower surfaces of the die and the leads, whereby exposed portions of the leads form the only externally accessible I/O contacts for a resulting integrated circuit package.

8. (New) A method as recited in claim 7 further comprising mounting the package on a circuit board such that the lower surface of the die is in direct contact with a heat sink formed on the circuit board.

9. (New) A method as recited in claim 7 further comprising applying solder to exposed portions of the leads.

10. (New) A method as recited in claim 9 further comprising soldering the lower surfaces of the leads to a circuit board to electrically connect the package to the circuit board.